

L Number	Hits	Search Text	DB	Time stamp
1	141971	(laminate laminating lamination laminated) with (substrate carrier board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/12 02:25
2	3266	antenna with (trace wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/12 02:26
3	214	((laminate laminating lamination laminated) with (substrate carrier board)) and (antenna with (trace wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/12 02:26
4	2393296	(semiconductor die chip ic dice (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/12 02:26
6	5081	antenna same (trace wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/12 02:26
5	136	((((laminate laminating lamination laminated) with (substrate carrier board)) and (antenna with (trace wiring))) and ((semiconductor die chip ic dice (integrated adj circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/12 02:28
7	96	(((((laminate laminating lamination laminated) with (substrate carrier board)) and (antenna with (trace wiring))) and ((semiconductor die chip ic dice (integrated adj circuit)))) and (bond wire)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/12 02:28